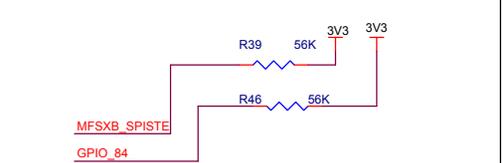
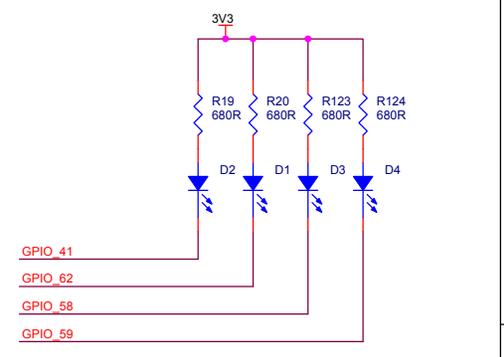
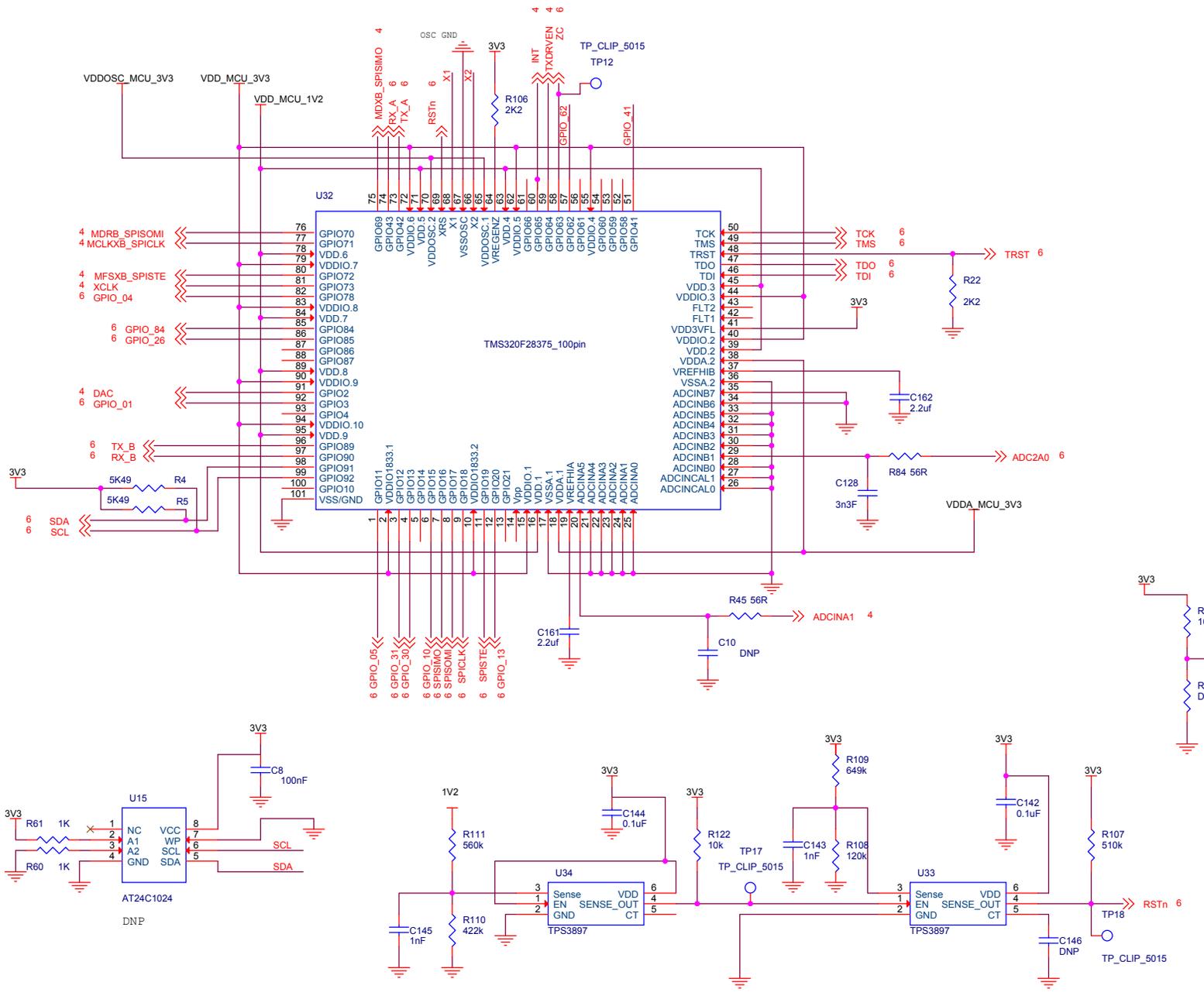


Notes/Revision Information

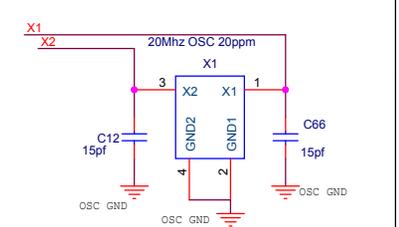
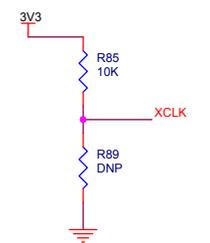
V0.03 - 11/22/2013
V0.04 - 2/21/2014
- Updated U35 package to DSG
V0.05 - 02/26/2014
p6
- Reassigned pin10(Connector J1) ZC
connection to GPIO_63(U32)
p4
- Pin 39 of U17 tied to GND
- Changed Pin 37 of U17 to floating
V0.06 - 08/28/2014
p5
- updated R100, L46, C140, C141,
L45 Values
- Added R121, L52, L53, C166, C167
p2
- Tied unused ADC pins to GND
- Added R122
- Added LED's D3, D4

01 - Title Page
02 - SOMPLC CEN
03 - SOMPLC-CEN Power
04 - AFE32
05 - BPF
06 - Connector

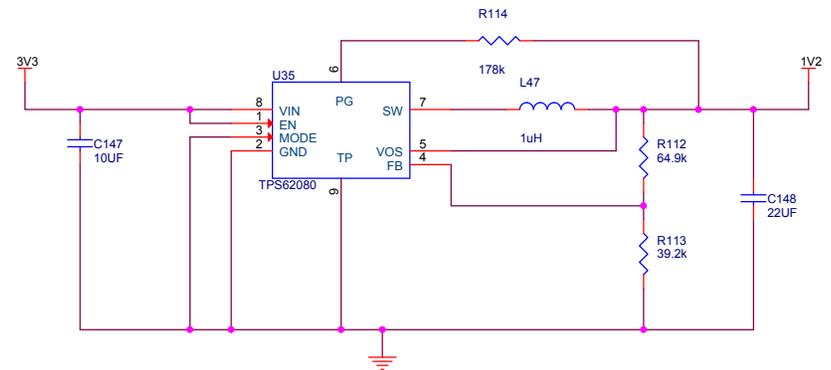
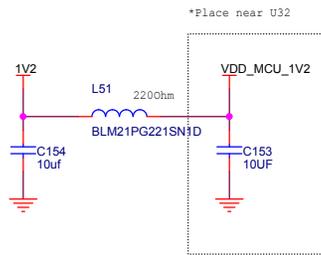
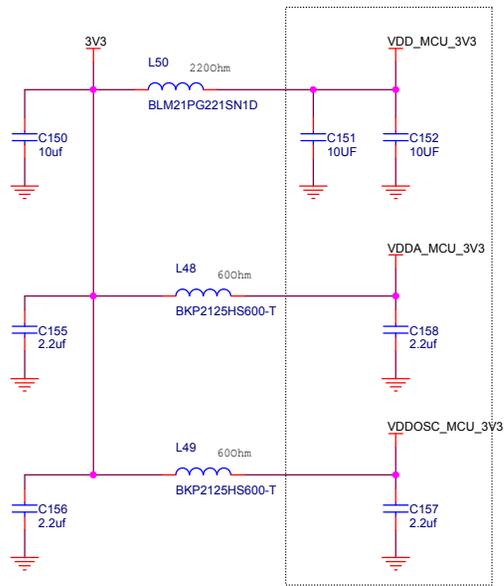
TIDEP0059		
Title:		
Page Contents:	01 - Title Page	
Size:B	<Doc>	Revision: 0.5
Date:	Monday, March 02, 2015	Sheet 1 of 6



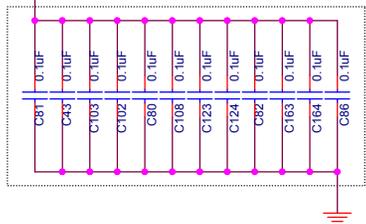
Default Bootmode Setting:
MFSXB_SPISTE:1
GPIO_84:1



TIDEP0059			TI
Title:			
Page Contents: 02 - TMS320F28375			
Size: B	<Doc>	Revision: 0.5	
Date: Monday, March 02, 2015	Sheet 2 of 6		

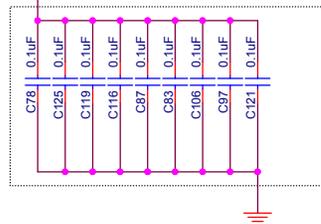


VDD_MCU_3V3 *Place near U32 Pins 2, 10, 15, 40, 44, 55, 62, 72, 79, 83, 90, 94

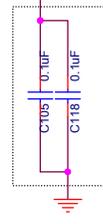


*Place near U32

VDD_MCU_1V2 *Place near U32 Pins 16, 39, 45, 63, 71, 78, 84, 89, 95

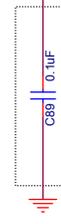


VDDOSC_MCU_3V3



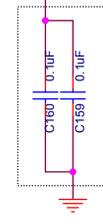
*Place near U32 Pins 65, 70

3V3



*Place near U32 Pin 41

VDDA_MCU_3V3



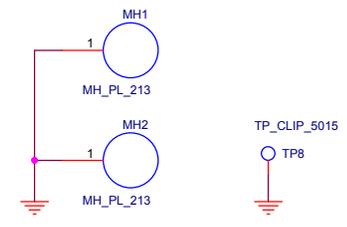
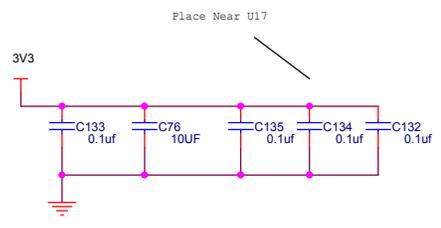
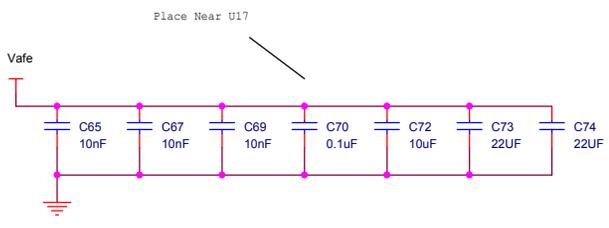
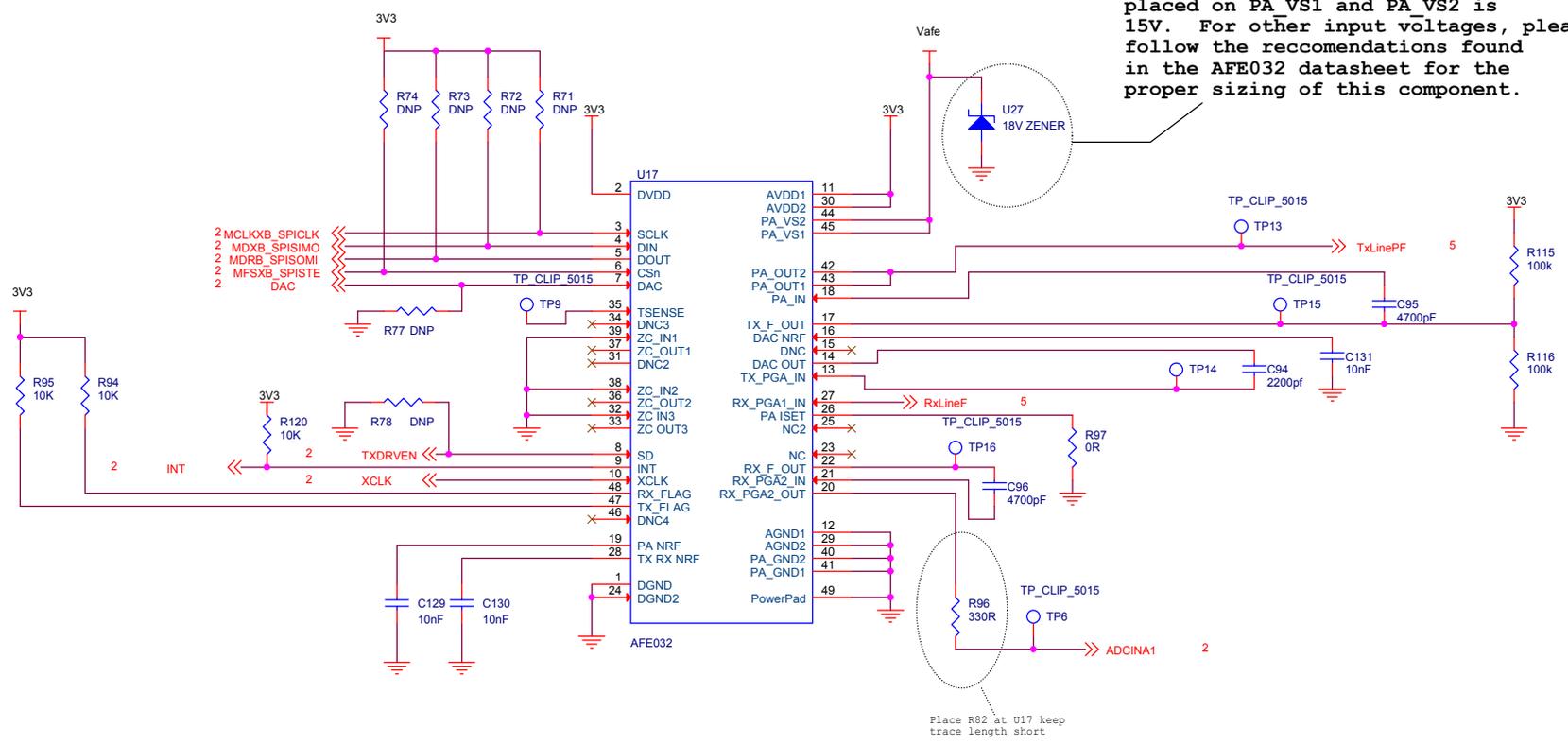
*Place near U32 Pins 18, 38

TIDEP0059

TI

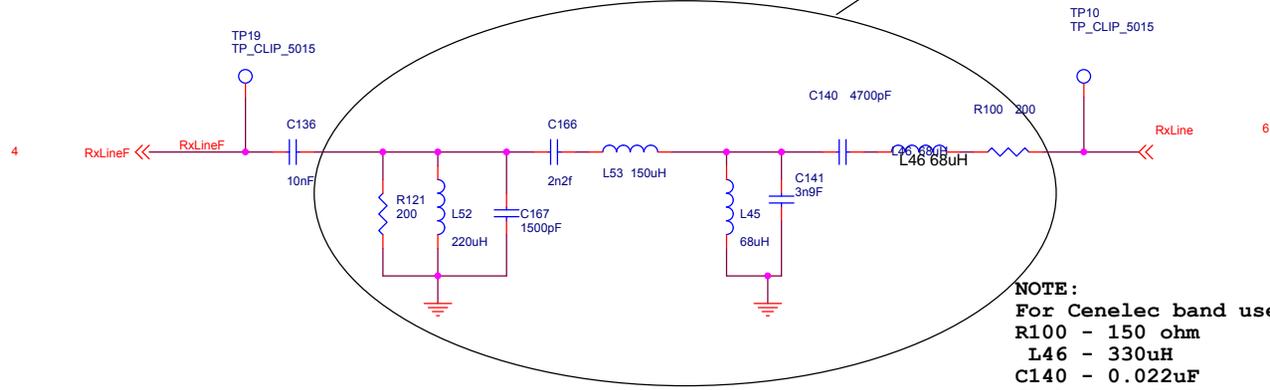
Title: U		Revision: 0.5
Page Contents: 03 - TMS320F28375 Power		Revision: 0.5
Size: B	<Doc>	Revision: 0.5
Date: Monday, March 02, 2015	Sheet 3 of 6	

NOTE: In this configuration the voltage placed on PA_VS1 and PA_VS2 is 15V. For other input voltages, please follow the recommendations found in the AFE032 datasheet for the proper sizing of this component.

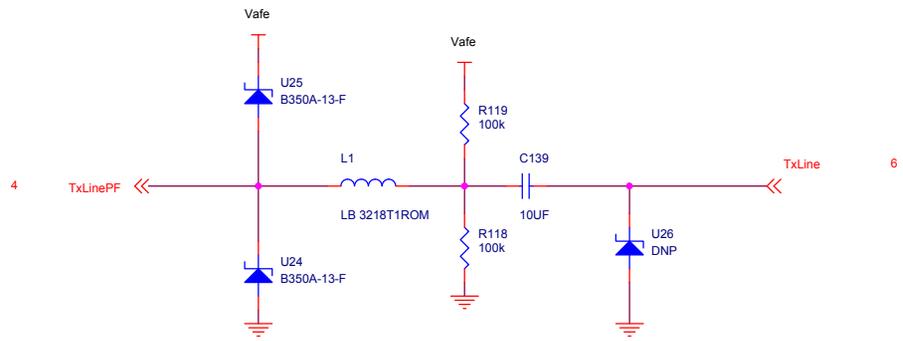


TIDEP0059		TI
Title: C		
Page Contents: 04 EAFE032		
Size: B	<Doc>	Revision: 0.5
Date: Monday, March 02, 2015	Sheet 4 of 6	

NOTE: Use Values below for CENELEC Band



NOTE:
 For Cenelec band use values below:
 R100 - 150 ohm
 L46 - 330uH
 C140 - 0.022uF
 C141 - 0.033uF
 L45 - 180uH
 L53 - 1mH
 C166 - 8200pF
 C167 - 0.015uF
 L52 - 470uH
 R121 - 150 ohm



Title: TIDEP0059		TI	
Page Contents: 05 - BPF		Revision: 0.5	
Size: B	<Doc>	Date: Monday, March 02, 2015	
		Sheet 5 of	6

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